



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model

[List multiple models if applicable.]

HP Compaq 8200 Elite All-in-One Business PC

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries PCA (1), wireless keyboard (2), wireless mouse (2)	up to 5
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries mercury lamps in display	4
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	1
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		0
External electrical cables and cords	power cord	1
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	Speakers L & R (2), external power supply (1)	3
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0

Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Screw driver	2# X10
Screw driver	1# X10
Box cutter/Knife (for opening the power supply)	

3.0 Product Disassembly Process

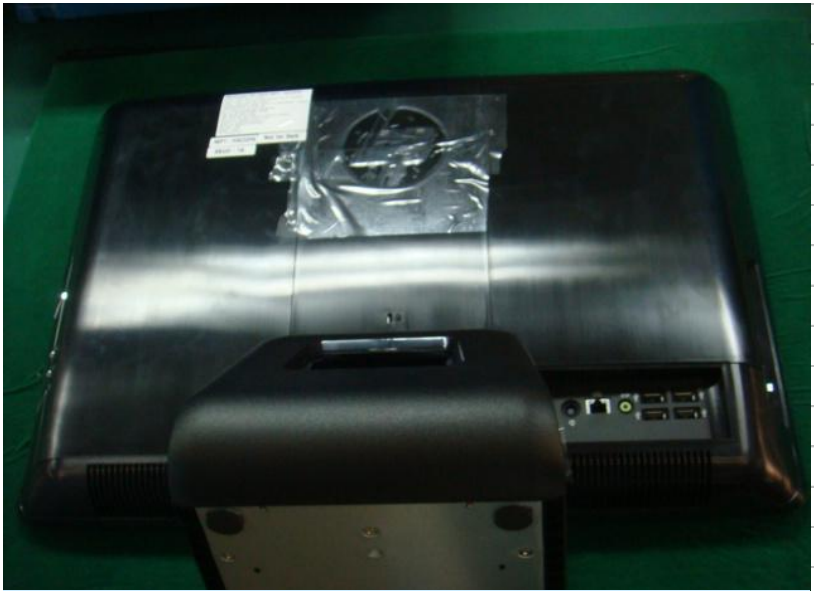
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Please refer to the graphical instructions below in section 3.2.
- 2.
- 3.
- 4.
- 5.
- 6.
- 7.
- 8.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

Figure 1 : Mechanical parts disassembly

- 1) Place the system



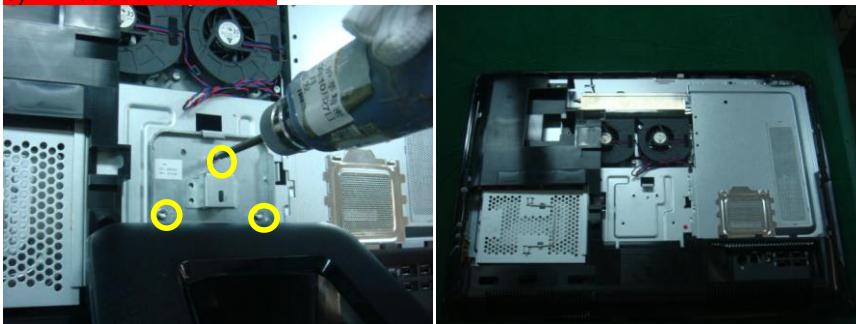
Place the unit on the work table as the picture

2) Disassemble hinge cover & R/L access door..



Disassemble the hinge cover with HP logo first and the disassemble the R/L access door

3) Disassemble stand



Disassemble the 3pcs screws of Stand then take stand away as the picture2 shows

4) Disassemble rear cover

EL-MF877-00

Template Revision B



Remove the eight screws of the rear cover then disassemble the rear cover

5) Disassemble CPU cover and stand shielding



Disassemble CPU cover and stand shielding

6) Disassemble HDD and ODD



Remove the screw of HDD cage and disassemble HDD then disassemble ODD

8) Disassemble speaker



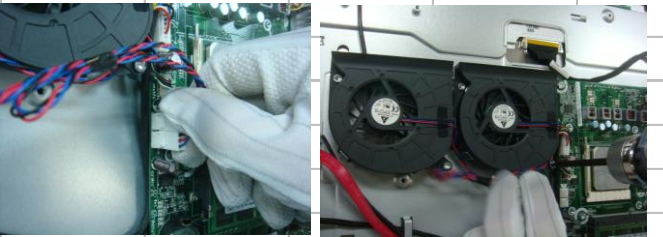
Remove 4pcs screw of speaker and then take out of speakers

9) Disassemble CPU thermal module



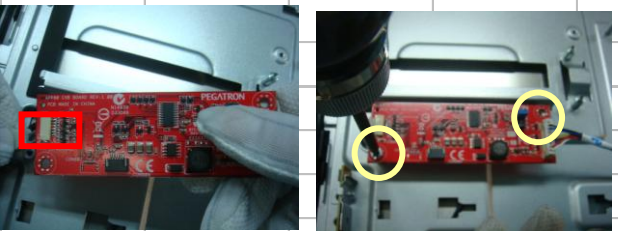
Remove 6psc screws of CPU thermal module then take out of it

10) Disassemble FAN



Pull out of the cable and then disassemble the fan

11) Disassemble Converter board



Pull out of the cable and move the screws of converter board then take out of the board

12) Disassemble the power switch card



Unplug the power switch cable and remove the screw then disassemble the card

13) Unplug the cable



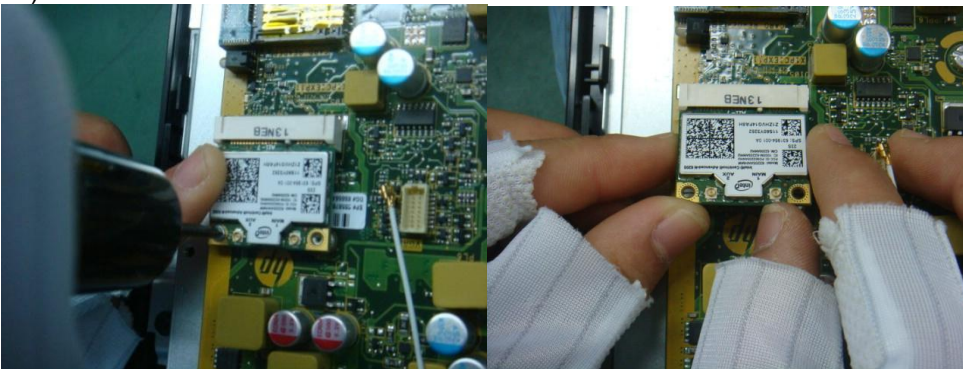
Unplug the SATA cable on MB side and disassemble the screws of the SATA cable. Last disassemble SATA cable and LVDS cable

14) Disassemble webcam



Remove the screw and disassemble the webcam card

15) Disassemble Wireless card



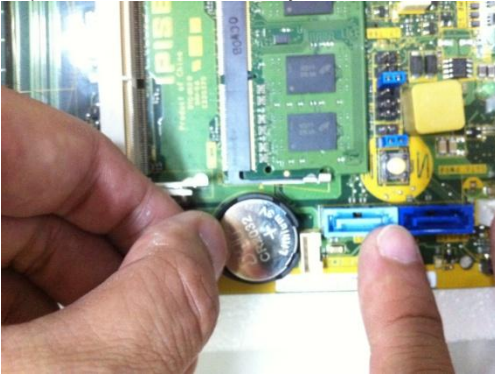
Take off the antenna and 2 screws.

16) Remove MB

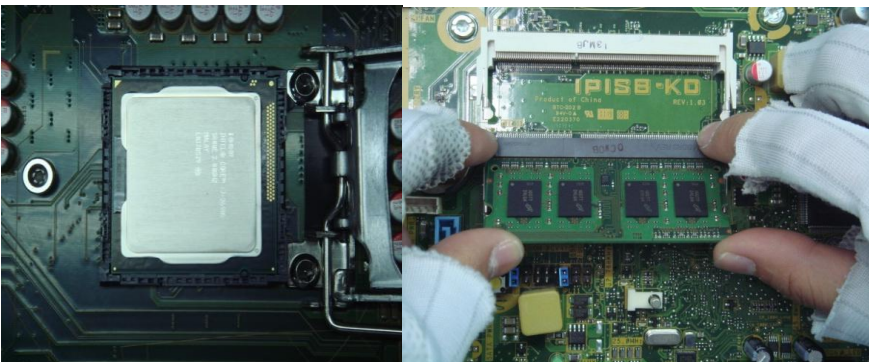


Take off 6 screws.

17) Remove RTC Battery



18) Disassemble CPU and DDR



Pull up the lever

19) Remove Antenna



Remove wireless antenna and power switch card from the unit

20) Separate BASE pan& bezel



Remove the screw and separate base pan and the panel

21) Disassemble the lens



Take out of the lens

22) Remove Mouse Battery



23) Remove Keyboard Battery



23) Remove power supply

